MSKSEMI 美森科
SEMICONDUCTOR

ESD TVS TSS MOV GDT PLED

LC03-3.3-MS

Product specification

Features

- Ultra low leakage: nA level
- Operating voltage: 3.3V
- Low clamping voltage
- Complies with following standards:
  - – IEC 61000-4-2 (ESD) immunity test
    Air discharge: ±30kV
    Contact discharge: ±30kV
  - – IEC61000-4-4 (EFT) 40A (5/50ns)
  - – IEC61000-4-5 (Lightning) 100A (8/20μs)
- RoHS Compliant

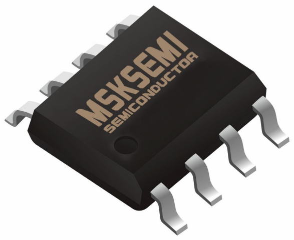
Mechanical Characteristics

- Package: SOP--8
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:500pcs
- Reel Size:7 inch

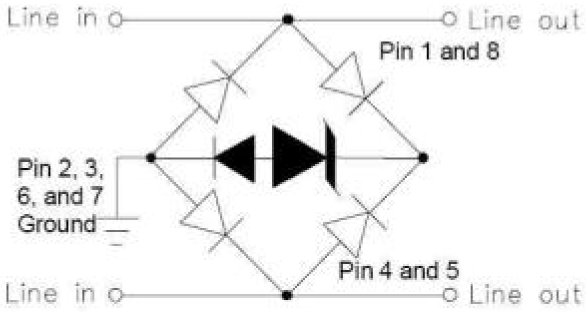
Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

Reference News

SOP-8	Marking
	

Pin Configuration



Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	**Symbol**	**Value**	**Unit**
Peak Pulse Power (8/20μs)	Ppp	1800	W
ESD per IEC 61000−4−2 (Air)	V_{ESD}	± 30	Kv
ESD per IEC 61000−4−2 (Contact)		± 30	
Operating Temperature Range	T_J	-55 to +125	℃
Storage Temperature Range	T_{STJ}	-55 to +150	℃

Electrical Characteristics(TA=25°C unless otherwise specified)

Part Number	**V_{RWM} (V)**	**V_{BR} (V)**	**I_T (mA)**	**V_C @50A**	**Vc**		**I_R μA (Max)**	**(Pf) C (Typ.)**
					(Max)	**(@A)**		
LC03-3.3-MS	3.3	3.5	1	12	18	100	1	25

Characteristic Curves

Fig1. 8/20μs Pulse Waveform

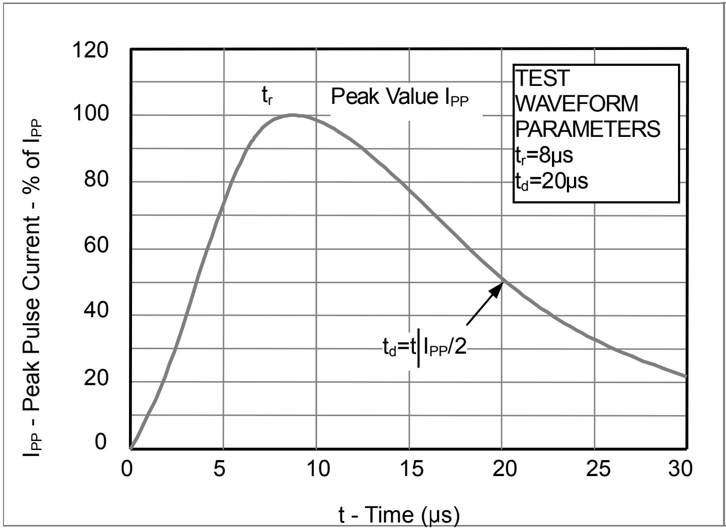


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

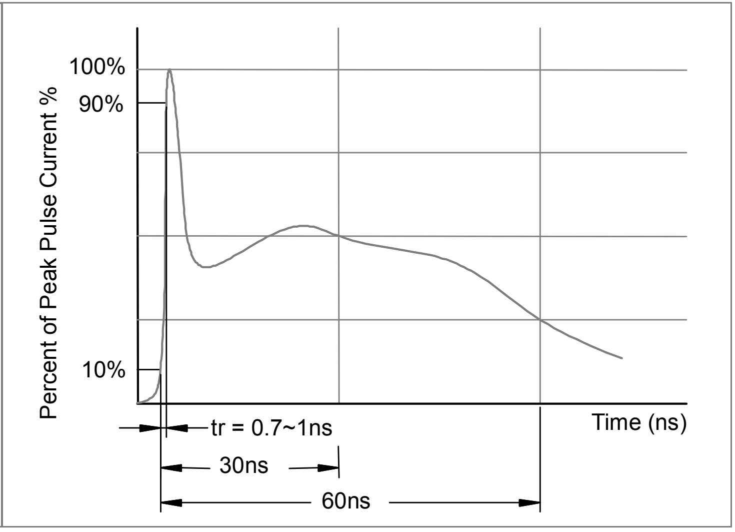
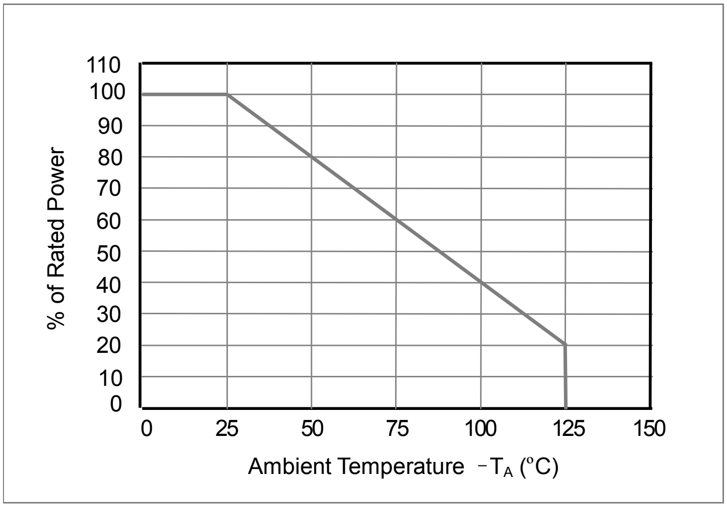
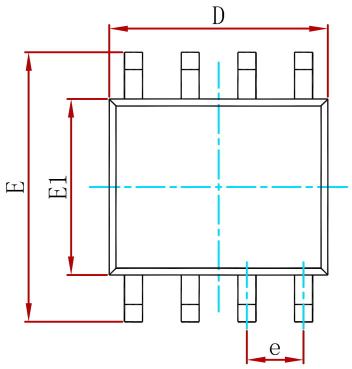
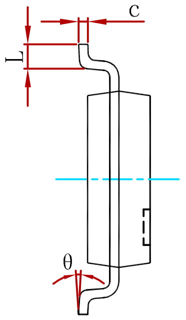


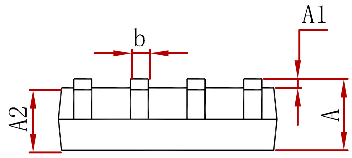
Fig3. Power Derating Curve



PACKAGEMECHANICALDATA

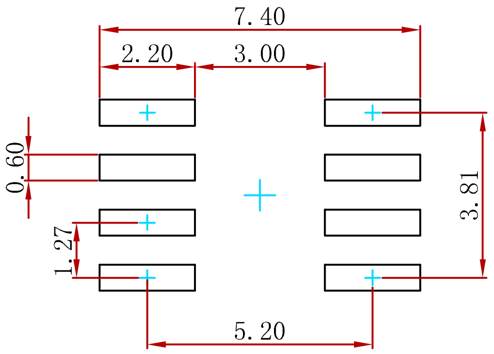






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	**Max**	**Min**	**Max**
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270（BSC）		0.050（BSC）	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Order information

Orderable Device	Package	Packing Option
LC03-3.3-MS	SOP-8	500PCS

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